



Liquid Crystal Thin Films: Structures and Applications

Guest Editor:

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submissions:

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Message from the Guest Editor

Soft materials, in particular liquid crystals, assemble and reconfigure in response to external constraints. They provide a model system for fundamental physics questions and the development of novel applications. Investigating the properties of liquid crystal films can lead to the development of new means to control the assembly of colloidal objects. A better understanding of how these films behave when confined under particular conditions will provide a fascinating tool for the creation of a new generation of advanced materials that may respond to external conditions.

This issue highlights the properties of liquid crystal films and emphasizes their role in the development of novel applications. We are inviting submissions exploring the latest advances in studying the properties of liquid crystal films, including bulk and surface properties that can lead to potential applications in the future. In particular, we encourage the submission of papers investigating a broad range of liquid crystal mesophases. Reviews that succinctly analyze recent progress in the field will also be considered.

- confinement
- thin films
- interfaces
- directed assembly
- liquid crystal devices





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Message from the Editor-in-Chief

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